

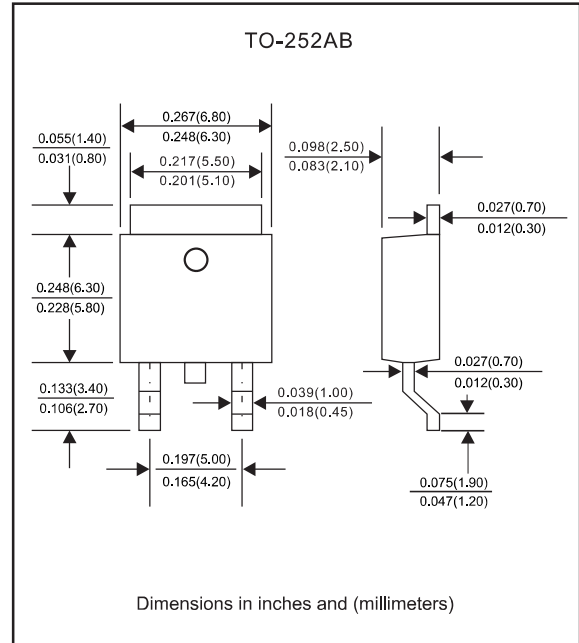
Features

- Batch process design, excellent power dissipation offers better reverse leakage current and thermal resistance.
- High current capability.
- Super fast reovery time for switching mode application.
- High surge current capability.
- Glass passivated chip junction.
- Lead-free parts meet environmental standards of MIL-STD-19500/228
- Compliant to Halogen-free

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, TO-252AB
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline



Maximum ratings and Electrical Characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig. 1	I_O			5.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			150	A
Reverse current	$V_R = V_{RRM}$ $T_J = 25^{\circ}\text{C}$	I_R			5.0	μA
	$V_R = V_{RRM}$ $T_J = 125^{\circ}\text{C}$				500	
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C_J		50		pF
Storage temperature		T_{STG}	-55		+150	$^{\circ}\text{C}$

SYMBOLS	V_{RRM} ^{*1} (V)	V_{RMS} ^{*2} (V)	V_R ^{*3} (V)	V_F ^{*4} (V)	t_{rr} ^{*5} (ns)	Operating temperature T_J , ($^{\circ}\text{C}$)
SF51YD	50	35	50	1.00	35	-55 to +150
SF52YD	100	70	100			
SF54YD	200	140	200			
SF56YD	400	280	400	1.30		
SF58YD	600	420	600	1.70		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@ $I_F=5.0\text{A}$

*5 Maximum Reverse recovery time, note 1

Note 1. Reverse recovery time test condition, $I_F=0.5\text{A}$, $I_R=1.0\text{A}$, $I_{RR}=0.25\text{A}$

Rating and characteristic curves (SF51YD THRU SF58YD)

Fig.1 Forward Current Derating Curve

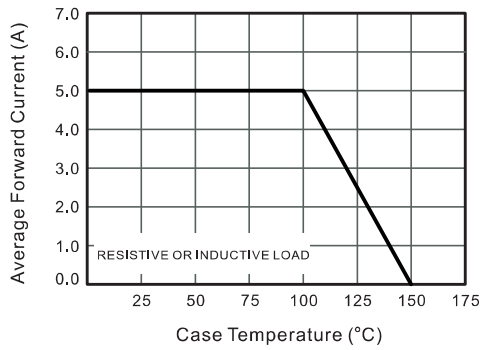


Fig.2 Typical Instantaneous Reverse Characteristics

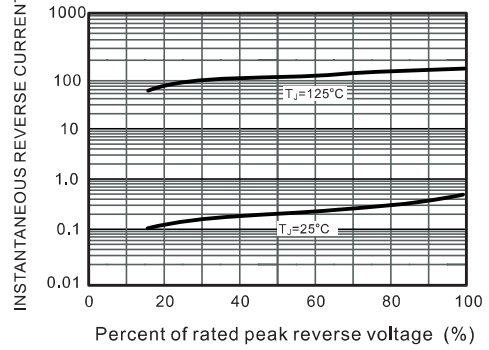


Fig.3 Typical Forward Characteristic

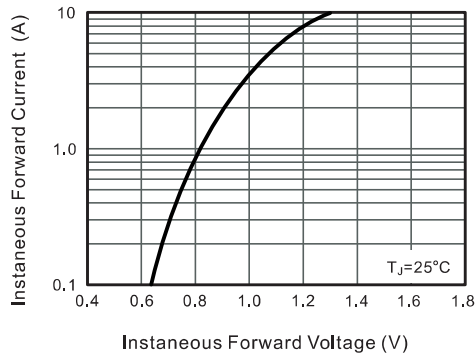


Fig.4 Typical Junction Capacitance

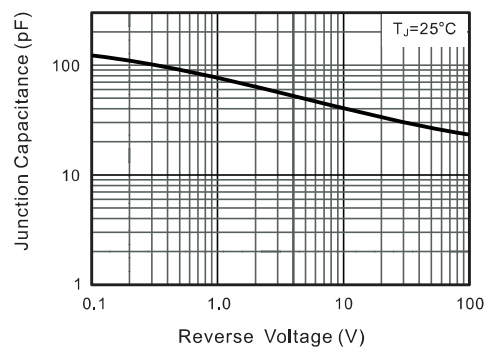


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

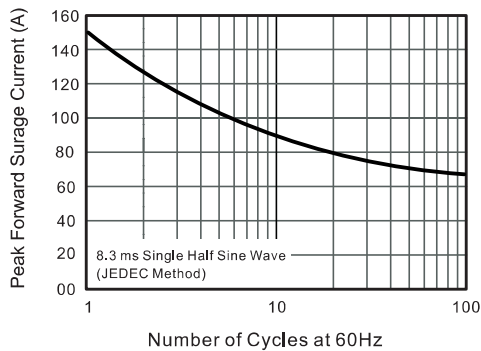
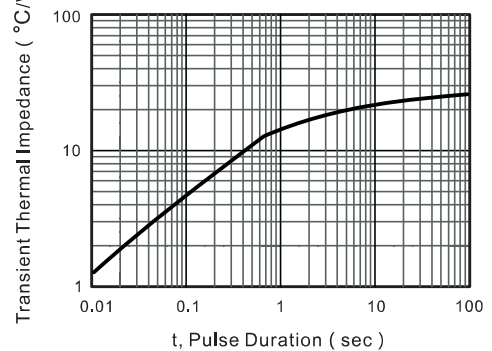
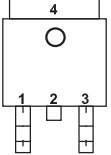
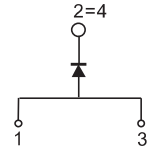


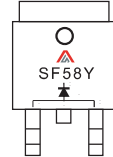
Fig.6- Typical Transient Thermal Impedance



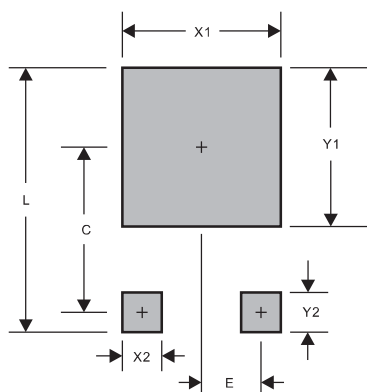
Pinning information

Simplified outline	Symbol
	

Marking

Type number	Marking code	Example
SF51YD	SF51Y	
SF52YD	SF52Y	
SF54YD	SF54Y	
SF56YD	SF56Y	
SF58YD	SF58Y	

Suggested solder pad layout



PACKAGE	TO-252AB
C	0.272(6.90)
E	0.091(2.30)
L	0.457(11.60)
X1	0.276(7.00)
X2	0.059(1.50)
Y1	0.276(7.00)
Y2	0.098(2.50)

Dimensions in inches and (millimeters)